

## TECHNICAL CHARACTERISTICS

### 1.General Characteristics

Dimensions: 17.40Lx16.50Wx2.70Hmm  
 Contact principle: Friction technology  
 Operating position: shaft up/down/Horizontal  
 Mounting System: SMT Type (without post)  
 Durability: 2,000 cycles min.

### 2.Mechanical characteristics:

Insulation material: LCP

### 3.Electrical Characteristics

Number of contacts : 8pins  
 contact resistance: 100m $\Omega$ /20mA  
 insulation resistance: >1000M $\Omega$ /500VDC

### 4.Solderability

wave: Not applicable  
 Vaporphase: 215°C, 30sec. Max  
 IR reflow: 250°C - 260°C, 5 sec. Max.  
 Manual soldering : 360°C, 3sec. Max

### 5.Environmental Characteristics

Operating temperature: -25°C~+85°C  
 Operating humidity : 10%~+95%RH  
 Storage temperature: -40°C~+85°C  
 Storage Humidity: 10%~95%RH  
 thermal shock: -40°C~+85°C, 5cycles  
 Damp Heat: 40°C, 90%RH, 10days.  
 Salt-Mist: 35°C, 5%NaCl, 24H

# Wellco T&C Co., Ltd.

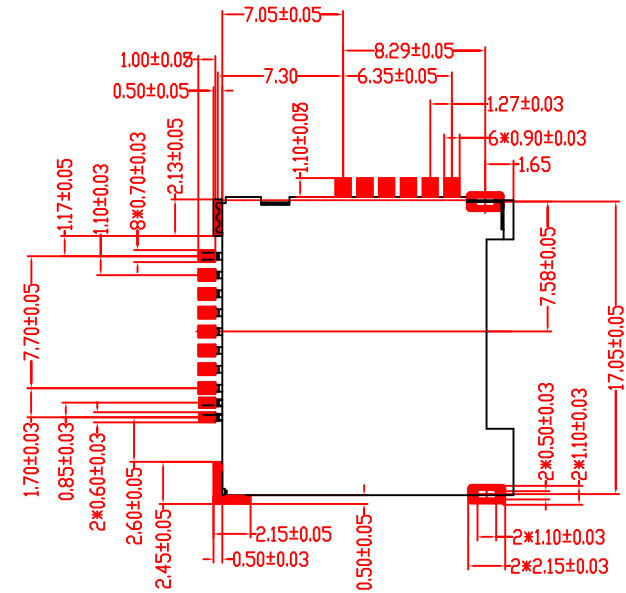
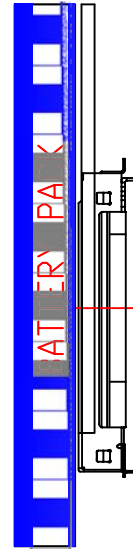
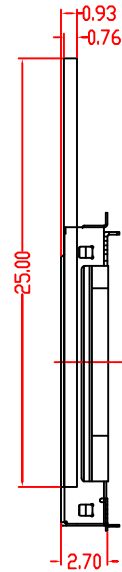
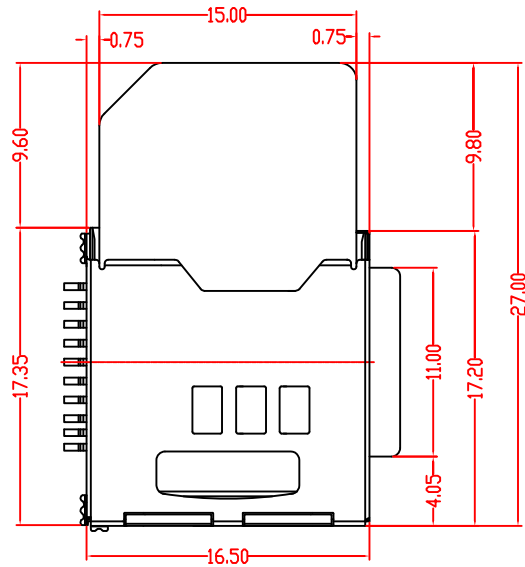
## SIM+TF Card Connector

### Model NO : 618

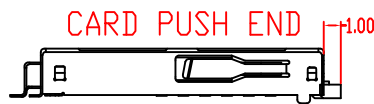
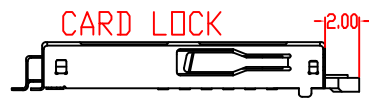
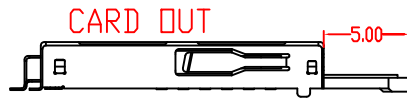
## Memory Card Connector

REVISION: 1.0

DATE: APR.12. 2007



PCB PATTERN



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**SIM+TF Card Connector**

**Model NO : 618**

**Memory Card Connector**

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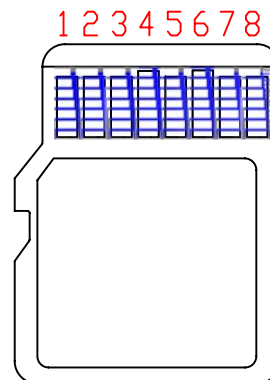
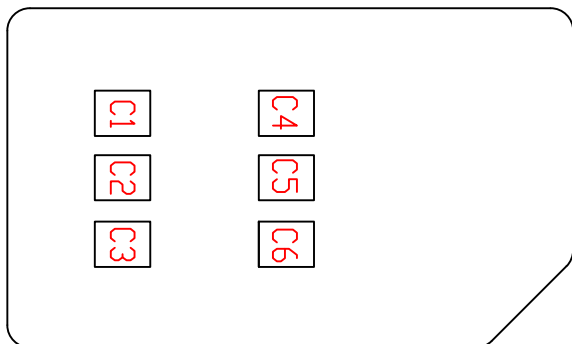
**DATE: APR.12. 2007**

SIM CARD

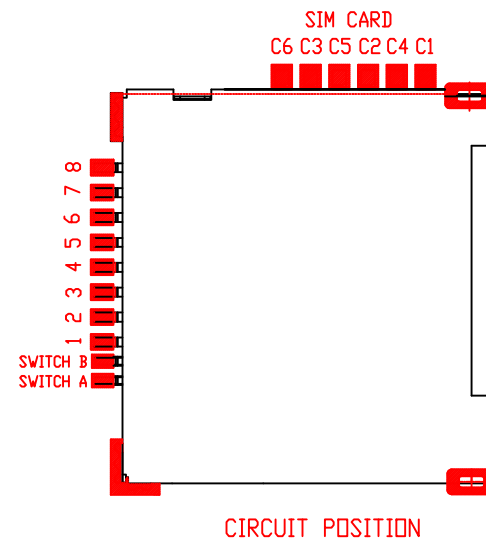
Pin No.	NAME
C1	ACC
C2	RST
C3	CNK
C4	CND
C5	VPP
C6	I/O

T-FLASH CARD

Pin No.	NAME	TYPE	DESCRIPTION
1	DAT2	I/O/PP	Date Line[bit2]
2	CD/DAT3	I/O/PP	Card Detect Date Line[bit3]
3	CMD	PP	DESCRIPTION
4	VDD	S	DESCRIPTION
5	CLK	I	DESCRIPTION
6	ASS	8	DESCRIPTION
7	DAT0	I/O/PP	DESCRIPTION
8	DAT1	I/O/PP	DESCRIPTION



T-FLASH CARD



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